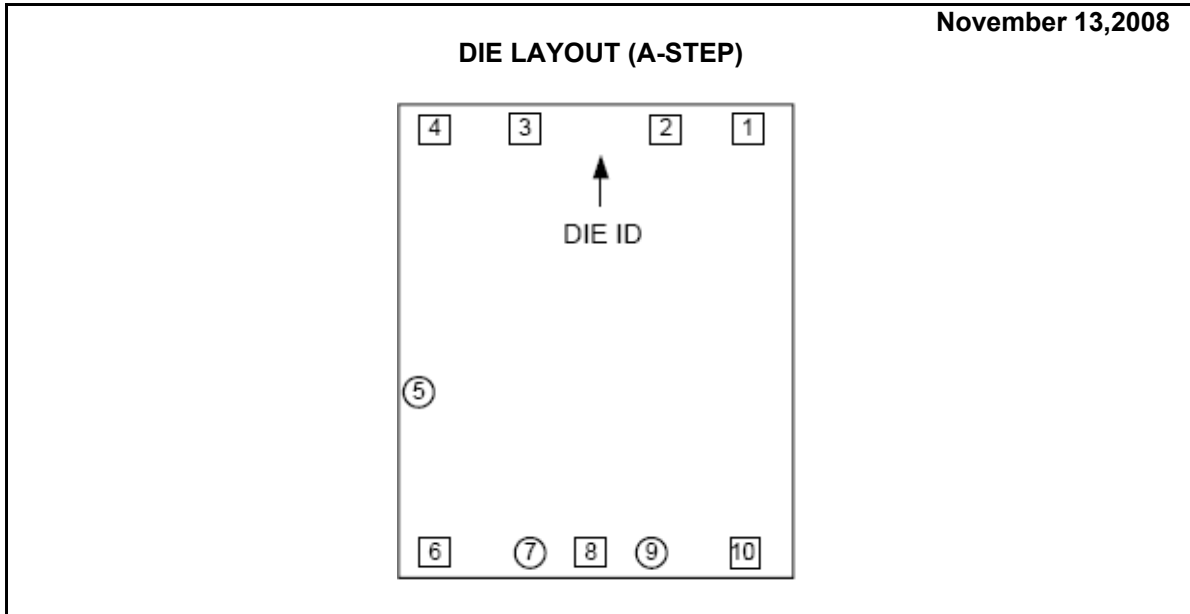


**LM95172QA2 MDA MCD2670A
13-BIT TO 16-BIT DIGITAL TEMPERATURE SENSOR WITH 3-WIRE INTERFACE**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM95172A	Bond Pad Opening Size (min)	69 μ m x 69 μ m
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1143 μ m x 1607 μ m 45.0mils x 63.3mils	Back Side Connection	GND
Thickness	254 μ m Nominal		
Min Pitch	255 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

 (Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE		
		X	Y	X	Y	
Vdd Analog	1	497.75	728.80	69	x	69
Vdd IO	2	242.80	728.80	69	x	69
<u>OVERTEMP</u>	3	-147.35	728.80	69	x	69
SC	4	-497.75	728.80	69	x	69
NC	5	-	-	-	-	-
<u>CS</u>	6	-497.75	-728.80	69	x	69
NC	7	-	-	-	-	-
GND	8	0.00	-728.80	69	x	69
NC	9	-	-	-	-	-
SI/O	10	497.65	-728.80	69	x	69

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Notes

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